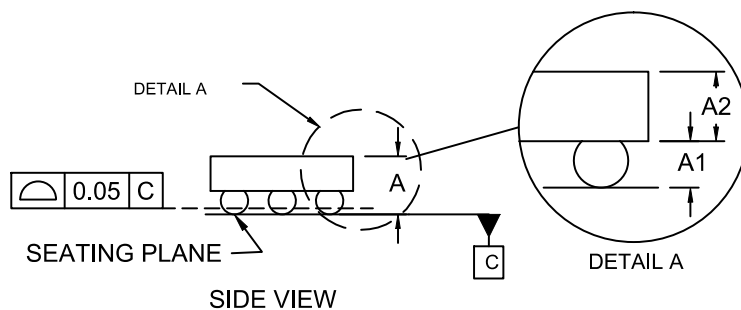
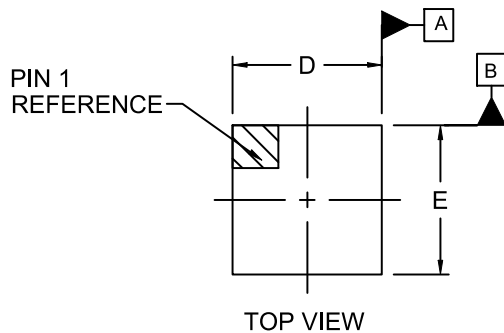


WLCSP9, 1.365x1.315x0.586
CASE 567VH
ISSUE O

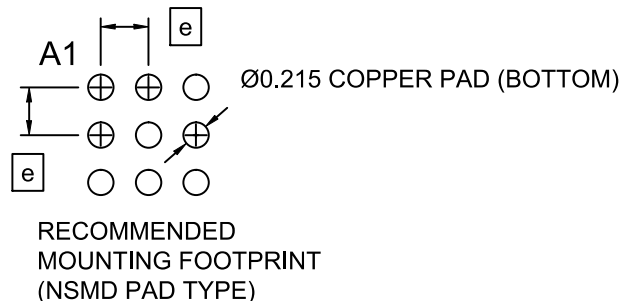
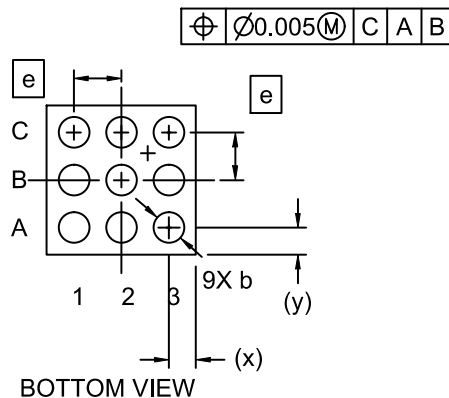
DATE 03 NOV 2017



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DATUM C APPLIES TO THE SPHERICAL CROWN OF THE SOLDER BALLS

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.548	0.586	0.624
A1	0.188	0.208	0.228
A2	0.360	0.378	0.396
b	0.240	0.260	0.280
D	1.335	1.365	1.395
E	1.285	1.315	1.345
e	0.40 BSC		
x	0.268	0.283	0.298
y	0.243	0.258	0.273



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DESCRIPTION:	WLCSP9, 1.365x1.315x0.586	PAGE 1 OF 1

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